EIPC European Institute of Printed Circuits

Global PCB market and local manufacturing: “Strategies to maintain profitability in the European PCB Industry”

EIPC Summer Conference 2016
Date: June 9 & 10, 2016
Location: Edinburgh, United Kingdom
Bonus Programme: Boat Trip Falkirk Wheel & The Scottish Canals

Presentations on the following topics are included in the conference programme:

- Management / Markets
  - Market forecasts and outlook
  - Status of the PCB industry today
  - Challenges and opportunities
- Embedding
- Embedding vs. conformal coating
- New interconnect developments
- High thermal conductivity substrates and power management applications
- New developments in flame retarded substrates
- The Internet of Things - meeting the interconnection demands
- New developments in imaging for reliable fine featured circuit boards
- Advanced microvia metallisation processes
- Interconnection processes for wearable electronics
- Imaging
- Plating
- Inspection
- Manufacturing methods
- Cleaning of PCBs/PCBAs
- 3D printing & printed electronics
- EMS/ODM market & technology trends for Europe
- Technology demands for PCBs in renewable energy applications
- Technology Roadmaps for various industry sectors: automotive, IT, defence, aerospace...
- Thermal management issues and solutions
- Drilling; laser and mechanical process developments
- Industry standards; IPC, UL and IECs
- Reliability of PCBs and assemblies, measurement and testing methods
- Environmental issues and legislation, e.g. updates on REACH and RoHS, material scarcity, novel flame retardants, lifecycle approaches and recycling
- High added value European PCB manufacturing for the OEM base
  - Power electronics: interconnect and substrate performance requirements
  - PCB laminates: new materials for high frequency and thermal performance e.g. for LED lighting
  - Imaging / LDI processes and equipment
  - Novel materials and processes
- Integrating electrical and optical interconnects in PCBs

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### CALL FOR PAPERS

**EIPC Summer Conference Edinburgh - June 9 & 10, 2016**  
*Global PCB market and local manufacturing: “Strategies to maintain profitability in the European PCB Industry”*

#### Topics

We invite you to submit a paper for one of the following topics:

- Management / Markets  
  - Market forecasts and outlook  
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  - Challenges and opportunities
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- Integrating electrical and optical interconnects in PCBs

Any other topic you feel may be of interest

#### Notes for speakers

The following guidelines are provided regarding the submittal of papers and how they are to be presented at the Conference:

- Papers should supply new technical, management or statistical information and not be presented for commercial purposes.
- All presentations should be made in English. If the author has problems with presenting in English, he or she should inform EIPC about this situation.
- Presentations should not make direct comparisons with competitors’ products.
- When the description of particular equipment is necessary for proper understanding of the process, it shall be confined to technical aspects.

- Presentations will be required as a WRITTEN TEXT (Word/PDF) file
- Illustrations, graphics, tables or pictures (including presenter’s photograph) have to be electronically delivered in standard format and in the appropriate resolution (75 dpi for electronic publication)

The author or presenter of an oral presentation will be offered a complimentary one day conference registration, valid on the day the author is invited to present.

#### Abstract guidelines

Abstracts should include the following:

- Title of Presentation
- Author Listing; first/last name, affiliation, mailing address, telephone, fax, e-mail
- Abstract text (max. 200 words)
- Biography: brief background on the principal/presenting author (max. 100 words)

#### Acceptance Criteria

Abstracts will be reviewed by the Programme Committee, consisting of experts from within our industry. The official language of the Conference is English, **NO** simultaneous translations will be provided.

Selections will be based on the following criteria:

- Contribution to the industry.
- The abstract should clearly describe the nature, content, key points, and significance of the proposed paper.
- Presentations are to be strictly non-commercial and must focus on technical merits of described processes.
- Proprietary and/or confidentiality issues as well as approvals should be determined at time of submission.

#### Deadlines

- 1 page Abstract: March 25, 2016
- Notification of Acceptance: April 1, 2016

Please send the abstract submission form to:  
Ms. S. Derhaag, email: sderhaag@eipc.org  
Tel +31-(0) 43-3440872, Fax -73

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